





Vectron's VT-702 Temperature Compensated Crystal Oscillator (TCXO) is a quartz stabilized, clipped sine wave output, temperature compensated oscillator, operating off either 1.8, 2.5, 3.0 or 3.3 volt supply, hermetically sealed 5x7 ceramic package.

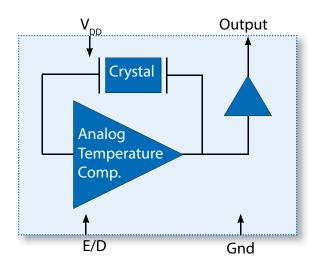
#### **Features**

- CMOS Output
- Output Frequencies to 54 MHz
- Fundamental Crystal Design
- · Gold over nickel contact pads
- Hermetically Sealed Ceramic SMD package
- Product is compliant to RoHS directive and fully compatible with lead free assembly

## Applications

- Wireless Communications
- Base Stations
- Point to point radios
- Broadband Access
- Test Equipment
- Handsets

### **Block Diagram**



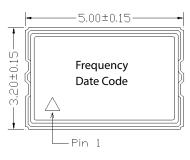
# **Specifications**

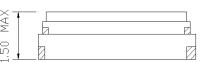
Table 1. Electrical Performance						
Parameter	Symbol	Min.	Тур	Max	Units	
Output Frequency,	$f_{_{\mathrm{O}}}$	4		54	MHz	
Supply Voltage <sup>1</sup>	V <sub>DD</sub>	+1.8	3, +2.5, +3.0 or +	+3.3	V	
Supply Current, 8 to 14.999MHz 15.000 to 25.9999MHz 26.000 to 40.000MHz	I <sub>DD</sub>		7			
Operating Temperature, ordering option	T <sub>OP</sub>		-30/75, -40/85		°C	
Stability Over TOP, ordering option		±2.	.5, ±3.0, ±4.0, ±	5.0	ppm	
Initial Accuracy	y ±0.5					
Power Supply Stability				±0.2	ppm	
Load Stability				±0.2	ppm	
Aging				±1.0	ppm/yr	
Output Logic 1 Logic 0	V <sub>ОН</sub> V <sub>OL</sub>	0.9*V <sub>DD</sub>		0.1*V <sub>DD</sub>	V	
Rise/Fall Time				5	ns	
Duty Cycle		45		55	%	
Output Load				10K II 10pF		
Phase Noise, 10.000MHz 10Hz 100Hz 1kHz 10kHz 10kHz			-91 -116 -137 -149 -150		dBc/Hz	
Start Up Time				10	ms	

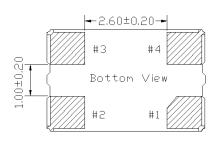
<sup>1.</sup> The VT-702 power supply pin should be filtered, eg, a 0.1 and 0.01uf capacitor

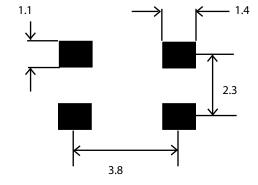
# **Outline Drawing**

# **Recommended Pad Layout**









Dimensions in mm

Table 2. Pinout							
Pin #	Symbol	Function					
1	E/D	Enable Disable					
2	GND	Electrical and Lid Ground					
3	$f_{o}$	Output Frequency					
4	$V_{_{ m DD}}$	Supply Voltage					

<sup>2.</sup> The Output is DC coupled

#### **Enable/Disable Function**

**Enable/Disable Feature:** The VT-702 has an enable/disable feature to which shuts down the oscillator and puts the output in to a high impdeance mode. If the Enable/Disable is left open or floating, the output is active"



### **Phase Noise for a Clipped Sinewave Output**



### **Maximum Ratings**

#### **Absolute Maximum Ratings and Handling Precautions**

Stresses in excess of the absolute maximum ratings can permanently damage the device. Functional operation is not implied or any other excess of conditions represented in the operational sections of this data sheet. Exposure to absolute maximum ratings for extended periods may adversely affect device reliability.

Although ESD protection circuitry has been designed into the VT-701, proper precautions should be taken when handling and mounting, VI employs a Human Body Model and Charged Device Model for ESD susceptibility testing and design evaluation.

ESD thresholds are dependent on the circuit parameters used to define the model. Although no industry standard has been adopted for the CDM a standard resistance of 1.5kOhms and capacitance of 100pF is widely used and therefor can be used for comparison purposes.

Table 3. Maximum Ratings			
Parameter	Symbol	Rating	Unit
Storage Temperature	T <sub>STORE</sub>	-40/85	°C
Supply Voltage	V <sub>DD</sub>		V
ESD, Human Body Model		TBD	V
ESD, Charged Device Model		TBD	V

Table 4. Environmental Compliance	
Parameter	Condition
Mechanical Shock	MIL-STD-883 Method 2002
Mechanical Vibration	MIL-STD-883 Method 2007
Temperature Cycle	MIL-STD-883 Method 1010
Solderability	MIL-STD-883 Method 2003
Fine and Gross Leak	MIL-STD-883 Method 1014
Resistance to Solvents	MIL-STD-883 Method 2015
Moisture Sensitivity Level	MSL1
Contact Pads	Gold over Nickel

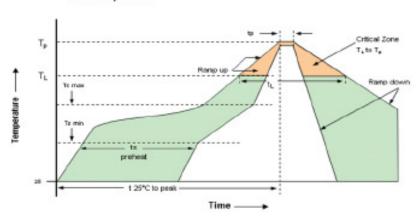
## **IR Reflow**

#### **Suggested IR Profile**

Devices are built using lead free epoxy and can be subjected to standard lead free IR reflow conditions shown in Table 5. Contact pads are gold over nickel and lower maximum temperatures can also be used, such as 220C.

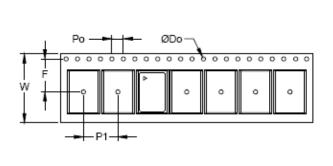
Table 5. Reflow Profile		
Parameter	Symbol	Value
PreHeat Time Ts-min Ts-max	t <sub>s</sub>	200 sec Max 150°C 200°C
Ramp Up	$R_{UP}$	3°C/sec Max
Time above 217C	t	150 sec Max
Time to Peak Temperature	t 25C to peak	480 sec Max
Time at 260C	t <sub>p</sub>	10 sec Max
Time at 240C	t <sub>P2</sub>	60 sec Max
Ramp down	$R_{_{DN}}$	6°C/sec Max

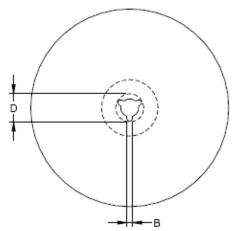
#### Solderprofile:

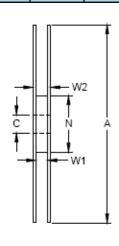


# **Tape & Reel**

Table 6. Tape and Reel Information												
Tape Dimensions (mm)				Reel Dimensions (mm)								
W	F	Do	Ро	P1	А	В	С	D	N	W1	W2	#/Reel
16	7.5	1.5	4	8	180	1.5	13	20.2	60	16.4	20.4	1000

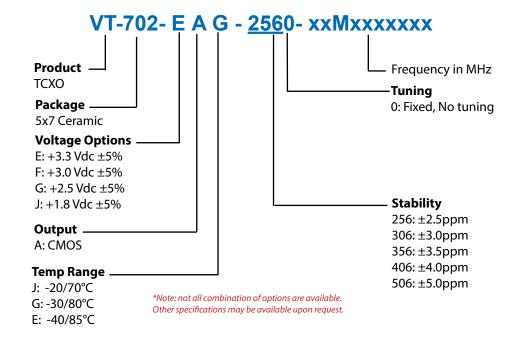






### **Ordering Information**

Table 7. Sta	ndard Frequ	iencies (MHz	:)						
10.000	10.245	12.504	12.800	13.000	13.568	14.000	14.31818	14.4844	14.7456
15.000	16.000	16.325291	16.36625	16.367667	16.3683	16.396	16.800	17.500	18.414
19.200	19.440	19.6608	19.680	19.800	20.000	20.910	21.250	23.104	24.000
24.5454	24.5535	24.576	25.000	25.600	26.000	27.000	27.456	28.800	32.768
40.000									



Example: VT-702-EAG-2560-26M0000000

\* Add **\_SNPBDIP** for tin lead solder dip Example: VT-702-EAG-2560-26M0000000\_SNPBDIP

## **Revision History**

Revision Date	Approved	Description
August 10, 2018	FB	Rev 0.4: Updated logo and contact information, added "SNPBDIP" ordering option



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